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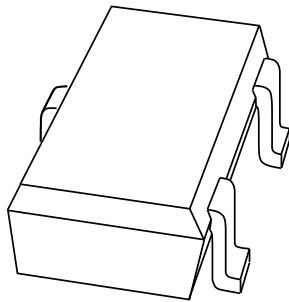
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DATA SHEET



BAP64-04W Silicon PIN diode

Product specification
Supersedes data of 2000 Jun 06

2001 Jan 29



Silicon PIN diode

BAP64-04W

FEATURES

- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Low series inductance
- For applications up to 3 GHz.

APPLICATIONS

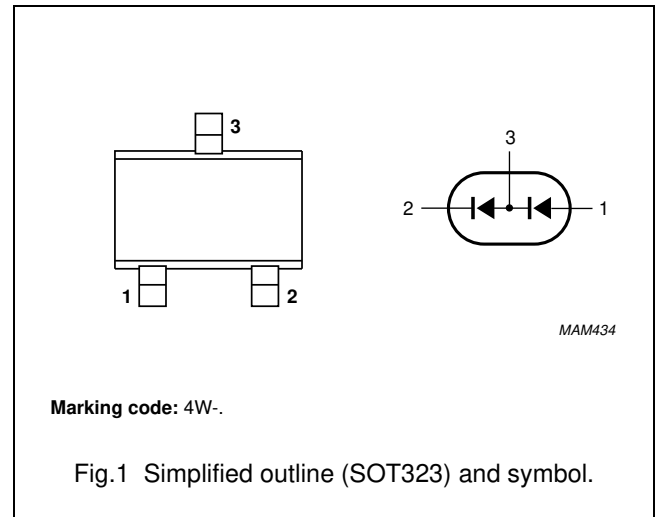
- RF attenuators and switches.

DESCRIPTION

Two planar PIN diodes in series configuration in a SOT323 small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	anode
2	cathode
3	common connection



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V_R	continuous reverse voltage		–	100	V
I_F	continuous forward current		–	100	mA
P_{tot}	total power dissipation	$T_s = 90\text{ °C}$	–	240	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–65	+150	°C

Silicon PIN diode

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ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
Per diode					
V_F	forward voltage	$I_F = 50\text{ mA}$	0.95	1.1	V
I_R	reverse current	$V_R = 100\text{ V}$	–	10	μA
		$V_R = 20\text{ V}$	–	1	μA
C_d	diode capacitance	$V_R = 0; f = 1\text{ MHz}$	0.52	–	pF
		$V_R = 1\text{ V}; f = 1\text{ MHz}$	0.37	–	pF
		$V_R = 20\text{ V}; f = 1\text{ MHz}$	0.23	0.35	pF
r_D	diode forward resistance	$I_F = 0.5\text{ mA}; f = 100\text{ MHz}; \text{note 1}$	20	40	Ω
		$I_F = 1\text{ mA}; f = 100\text{ MHz}; \text{note 1}$	10	20	Ω
		$I_F = 10\text{ mA}; f = 100\text{ MHz}; \text{note 1}$	2	3.8	Ω
		$I_F = 100\text{ mA}; f = 100\text{ MHz}; \text{note 1}$	0.7	1.35	Ω
τ_L	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}; R_L = 100\text{ }\Omega$; measured at $I_R = 3\text{ mA}$	1.55	–	μs
L_S	series inductance	$I_F = 100\text{ mA}; f = 100\text{ MHz}$	1.6	–	nH

Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

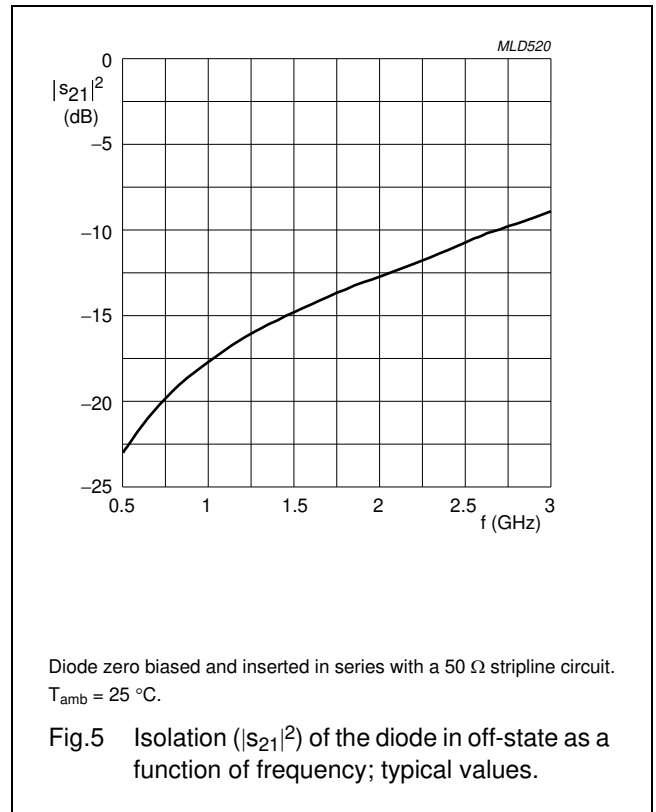
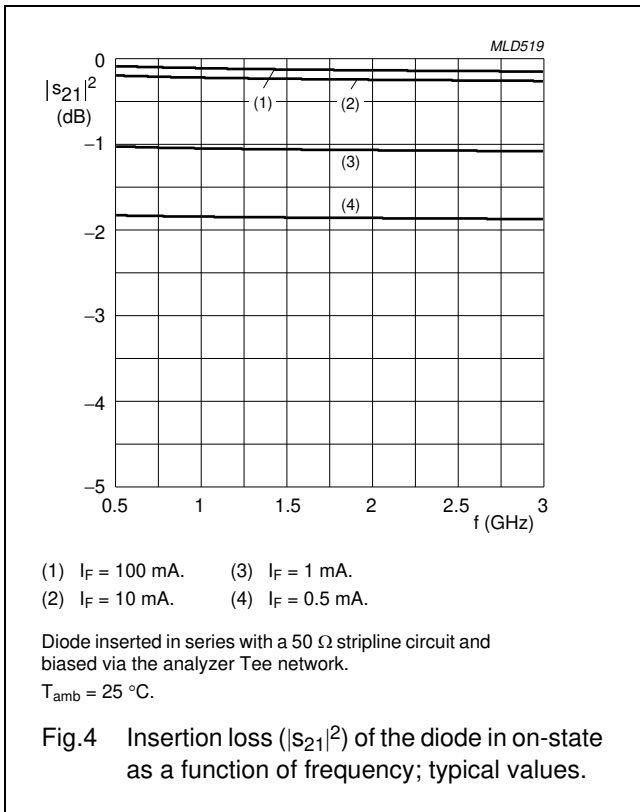
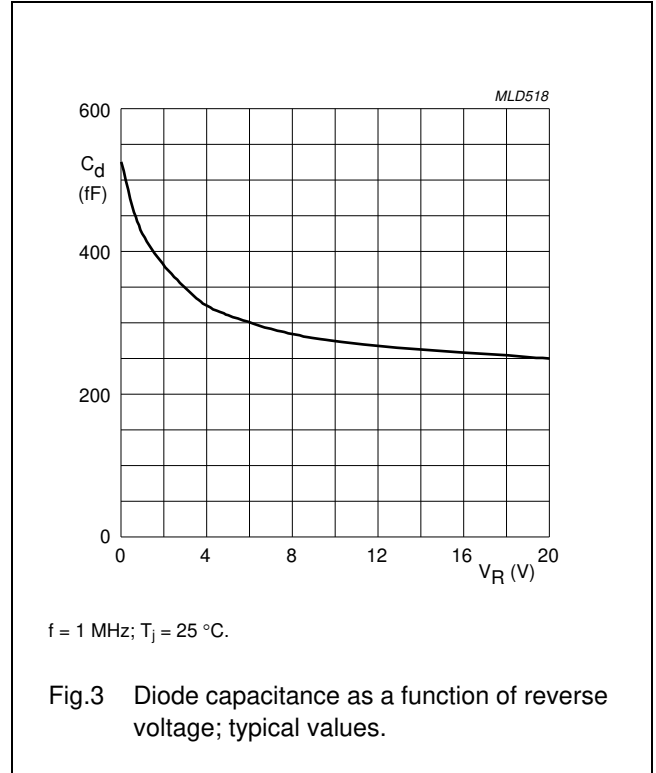
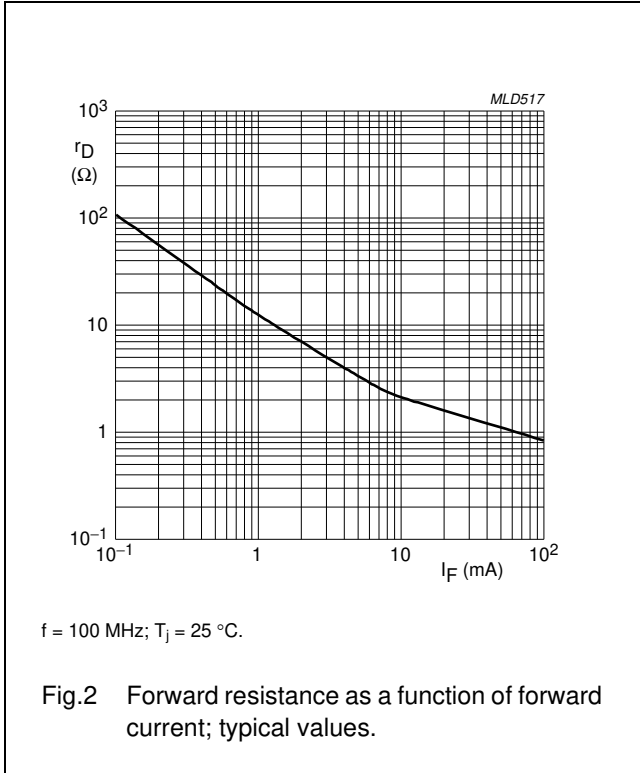
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point	250	K/W

Silicon PIN diode

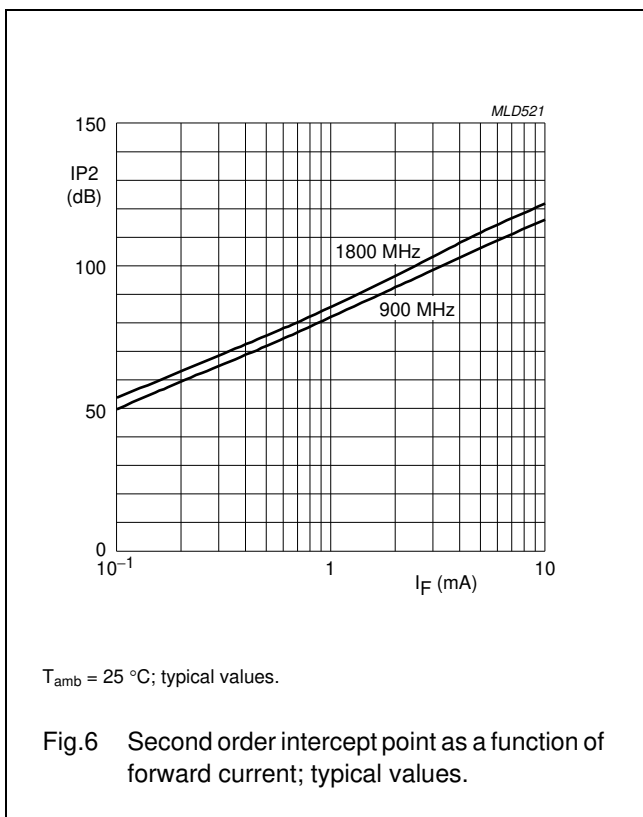
BAP64-04W

GRAPHICAL DATA



Silicon PIN diode

BAP64-04W



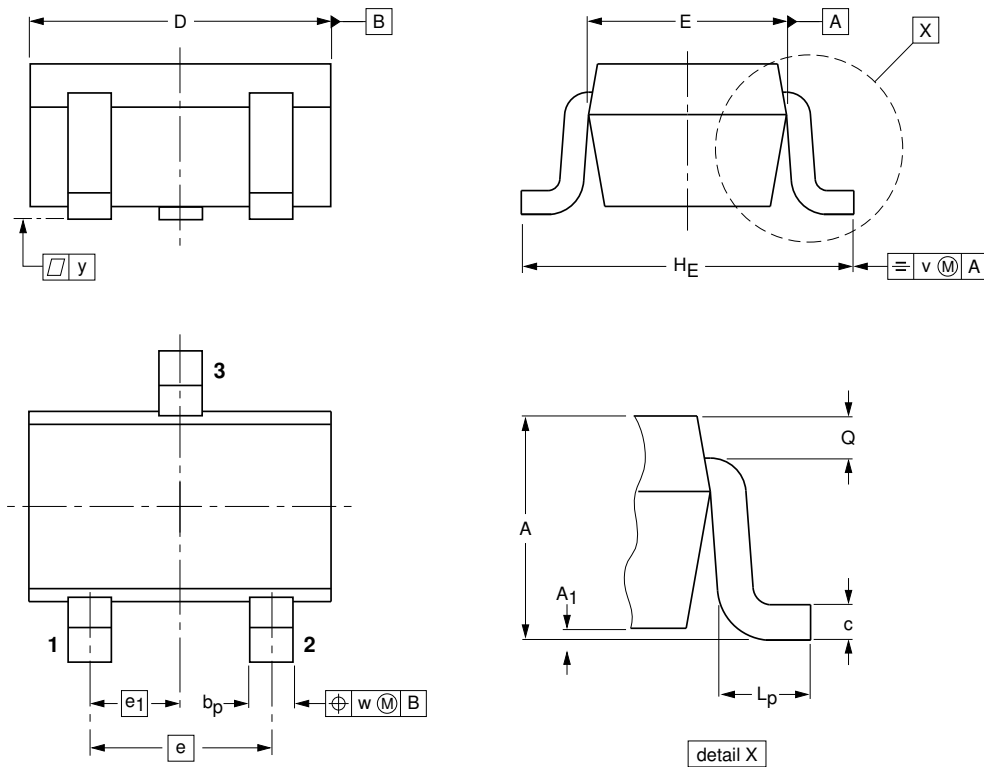
Silicon PIN diode

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PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			04-11-04 06-03-16

Silicon PIN diode

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Silicon PIN diode

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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